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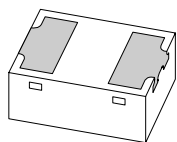
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Kind regards,

Team Nexperia



PMEG2005AELD

20 V, 0.5 A low V_F MEGA Schottky barrier rectifier

Rev. 1 — 10 May 2011

Product data sheet

1. Product profile

1.1 General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD882D leadless ultra small Surface-Mounted Device (SMD) plastic package with visible and solderable side pads.

1.2 Features and benefits

- Forward current: $I_F \leq 0.5$ A
- Reverse voltage: $V_R \leq 20$ V
- Low forward voltage: $V_F \leq 440$ mV
- Ultra small and leadless SMD plastic package
- AEC-Q101 qualified
- Solderable side pads
- Package height typ. 0.37 mm

1.3 Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- Reverse polarity protection
- Low power consumption applications
- Ultra high-speed switching

1.4 Quick reference data

Table 1. Quick reference data

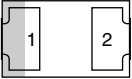
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{F(AV)}$	average forward current	square wave; $\delta = 0.5$; $f = 20$ kHz				
		$T_{amb} \leq 85$ °C	[1]	-	0.5	A
		$T_{sp} \leq 130$ °C	-	-	0.5	A
I_R	reverse current	$V_R = 10$ V	-	300	600	μ A
V_R	reverse voltage		-	-	20	V
V_F	forward voltage	$I_F = 500$ mA	[2]	365	440	mV

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for cathode 1 cm².

[2] Pulse test: $t_p \leq 300$ μ s; $\delta \leq 0.02$.



2. Pinning information

Table 2. Pinning			
Pin	Description	Simplified outline	Graphic symbol
1	cathode	 Transparent top view	 sym001
2	anode		

[1] The marking bar indicates the cathode.

3. Ordering information

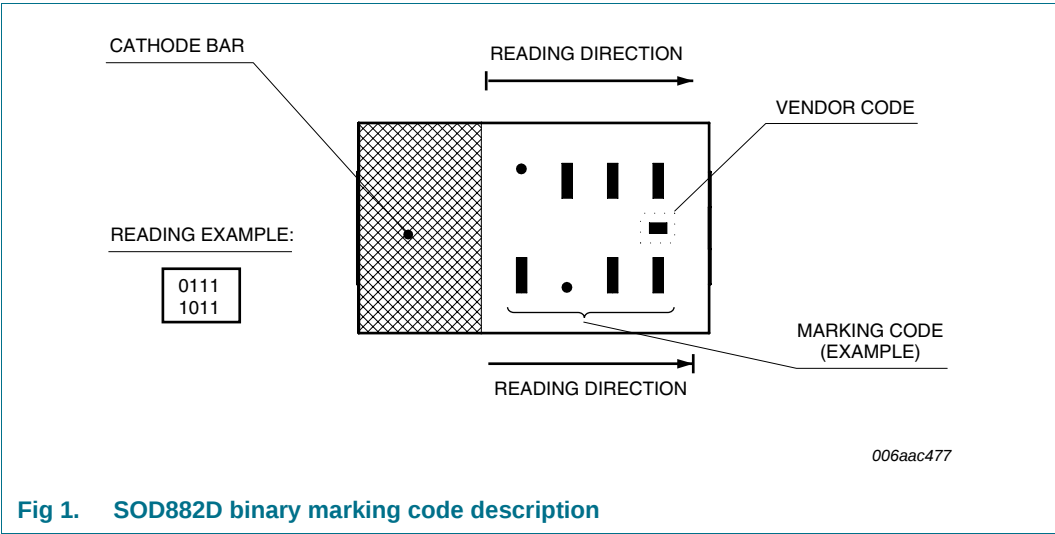
Table 3. Ordering information			
Type number	Package		
	Name	Description	Version
PMEG2005AELD	-	leadless ultra small plastic package; 2 terminals; body 1 × 0.6 × 0.4 mm	SOD882D

4. Marking

Table 4. Marking codes	
Type number	Marking code ^[1]
PMEG2005AELD	1001 0000

[1] For SOD882D binary marking code description, see [Figure 1](#).

4.1 Binary marking code description



5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_R	reverse voltage		-	20	V
$I_{F(AV)}$	average forward current	square wave; $\delta = 0.5$; $f = 20$ kHz			
		$T_{amb} \leq 85$ °C	[1] -	0.5	A
		$T_{sp} \leq 130$ °C	-	0.5	A
I_{FRM}	repetitive peak forward current	$t_p \leq 1$ ms; $\delta \leq 0.25$	-	2.5	A
I_{FSM}	non-repetitive peak forward current	square wave; $t_p = 8$ ms	[2] -	3	A
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	[3] -	340	mW
			[1] -	660	mW
			[4] -	1000	mW
T_j	junction temperature		-	150	°C
T_{amb}	ambient temperature		-55	+150	°C
T_{stg}	storage temperature		-65	+150	°C

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

[2] $T_j = 25$ °C prior to surge.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[4] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1][2]	-	-	370 K/W
			[1][3]	-	-	190 K/W
			[1][4]	-	-	125 K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[5]	-	-	50 K/W

[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

[4] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.

[5] Soldering point of cathode tab.

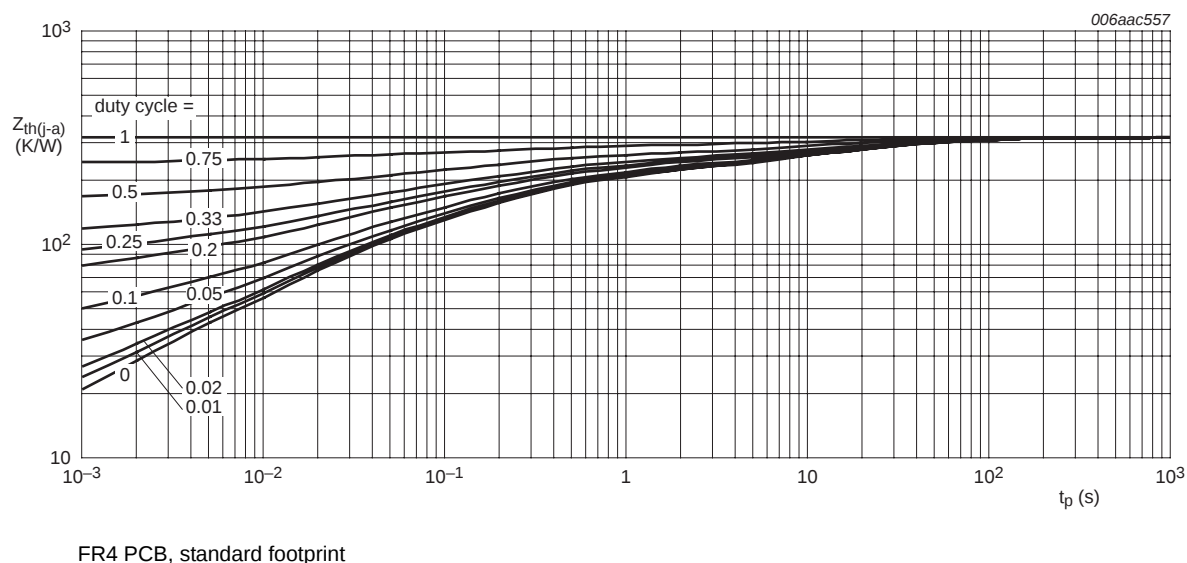
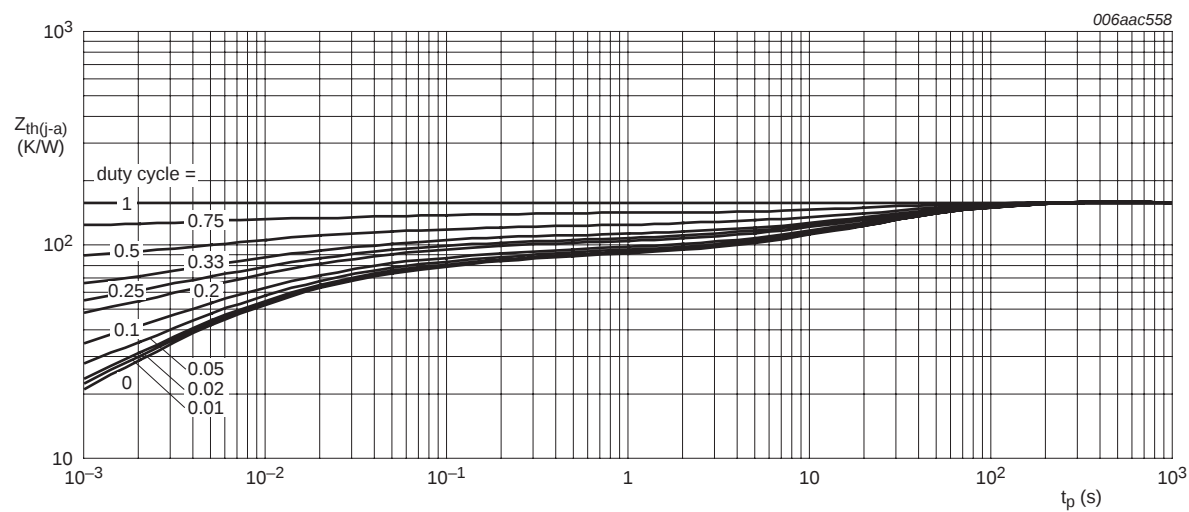
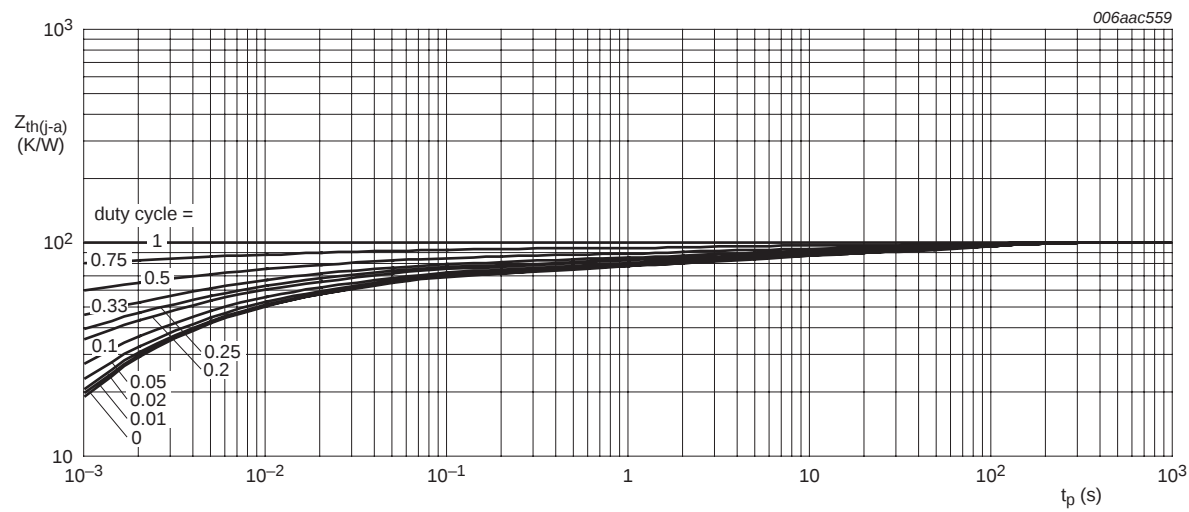


Fig 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm²

Fig 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



Ceramic PCB, Al₂O₃, standard footprint

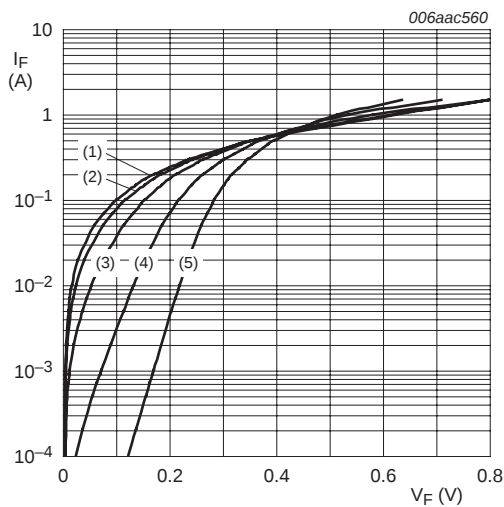
Fig 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

7. Characteristics

Table 7. Characteristics
 $T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

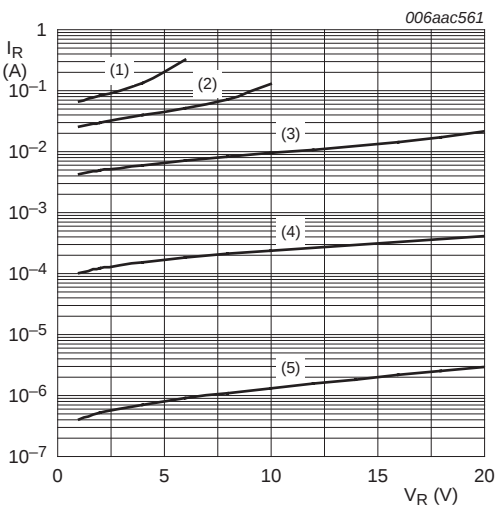
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_F	forward voltage		[1]			
		$I_F = 0.1\text{ mA}$	-	20	60	mV
		$I_F = 1\text{ mA}$	-	65	110	mV
		$I_F = 10\text{ mA}$	-	125	190	mV
		$I_F = 100\text{ mA}$	-	210	290	mV
I_R	reverse current	$V_R = 10\text{ V}$	-	300	600	μA
		$V_R = 20\text{ V}$	-	500	1500	μA
C_d	diode capacitance	$V_R = 1\text{ V}; f = 1\text{ MHz}$	-	19	25	pF
t_{rr}	reverse recovery time		[2]	6	-	ns

[1] Pulse test: $t_p \leq 300\text{ }\mu\text{s}$; $\delta \leq 0.02$.
[2] When switched from $I_F = 10\text{ mA}$ to $I_R = 10\text{ mA}$; $R_L = 100\text{ }\Omega$; measured at $I_R = 1\text{ mA}$.



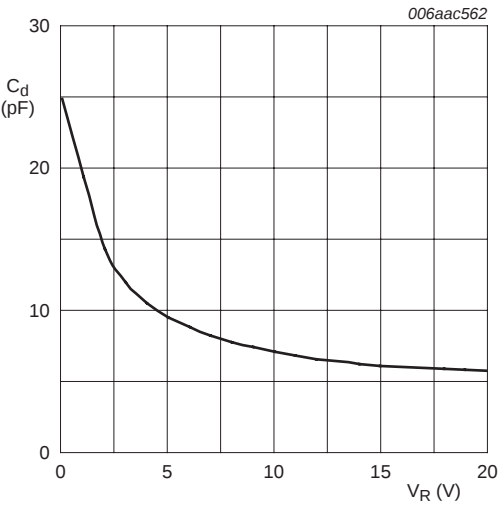
- (1) $T_j = 150\text{ }^{\circ}\text{C}$
- (2) $T_j = 125\text{ }^{\circ}\text{C}$
- (3) $T_j = 85\text{ }^{\circ}\text{C}$
- (4) $T_j = 25\text{ }^{\circ}\text{C}$
- (5) $T_j = -40\text{ }^{\circ}\text{C}$

Fig 5. Forward current as a function of forward voltage; typical values



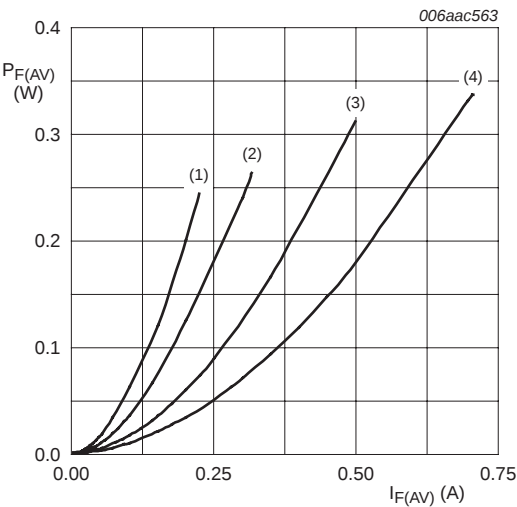
- (1) $T_j = 150\text{ }^{\circ}\text{C}$
- (2) $T_j = 125\text{ }^{\circ}\text{C}$
- (3) $T_j = 85\text{ }^{\circ}\text{C}$
- (4) $T_j = 25\text{ }^{\circ}\text{C}$
- (5) $T_j = -40\text{ }^{\circ}\text{C}$

Fig 6. Reverse current as a function of reverse voltage; typical values



$f = 1 \text{ MHz}; T_{\text{amb}} = 25 \text{ }^{\circ}\text{C}$

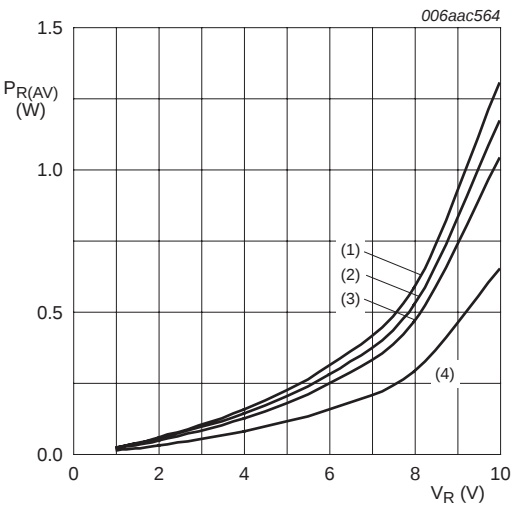
Fig 7. Diode capacitance as a function of reverse voltage; typical values



$T_j = 150 \text{ }^{\circ}\text{C}$

- (1) $\delta = 0.1$
- (2) $\delta = 0.2$
- (3) $\delta = 0.5$
- (4) $\delta = 1$

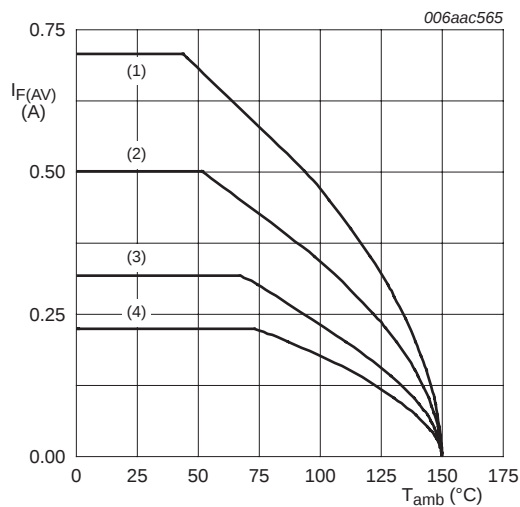
Fig 8. Average forward power dissipation as a function of average forward current; typical values



$T_j = 125 \text{ }^{\circ}\text{C}$

- (1) $\delta = 1$
- (2) $\delta = 0.9$
- (3) $\delta = 0.8$
- (4) $\delta = 0.5$

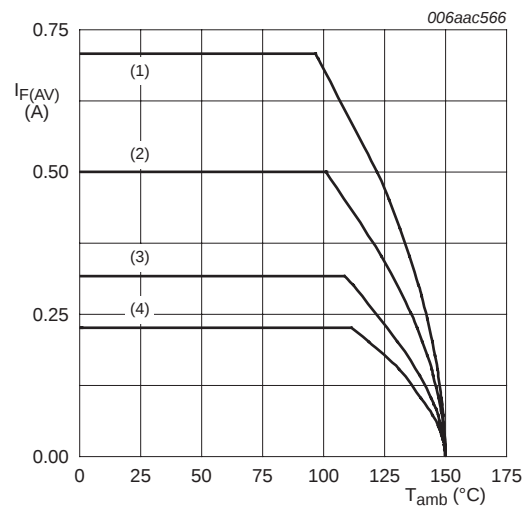
Fig 9. Average reverse power dissipation as a function of reverse voltage; typical values



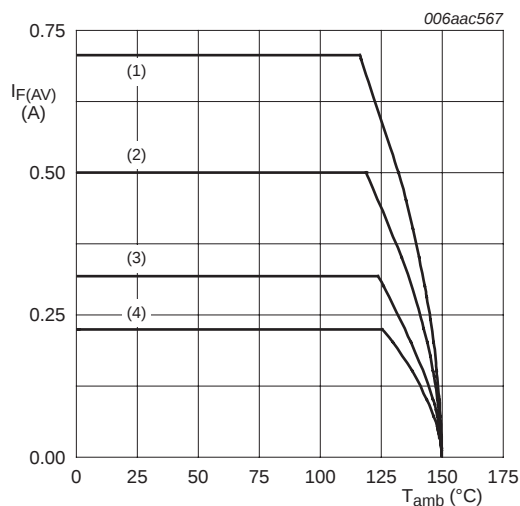
FR4 PCB, standard footprint

 $T_j = 150\text{ °C}$

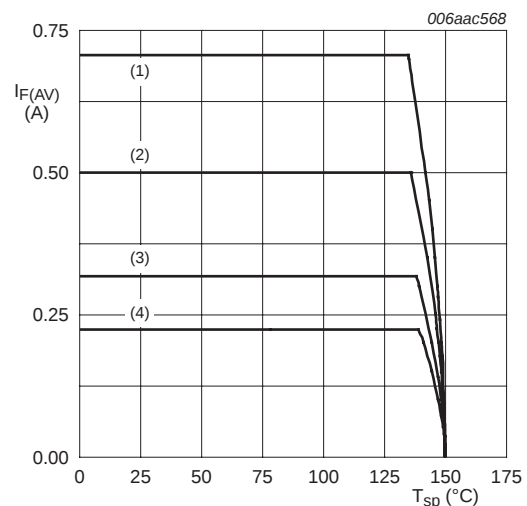
- (1) $\delta = 1$; DC
- (2) $\delta = 0.5$; $f = 20\text{ kHz}$
- (3) $\delta = 0.2$; $f = 20\text{ kHz}$
- (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig 10. Average forward current as a function of ambient temperature; typical valuesFR4 PCB, mounting pad for cathode 1 cm^2 $T_j = 150\text{ °C}$

- (1) $\delta = 1$; DC
- (2) $\delta = 0.5$; $f = 20\text{ kHz}$
- (3) $\delta = 0.2$; $f = 20\text{ kHz}$
- (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig 11. Average forward current as a function of ambient temperature; typical valuesCeramic PCB, Al_2O_3 , standard footprint $T_j = 150\text{ °C}$

- (1) $\delta = 1$; DC
- (2) $\delta = 0.5$; $f = 20\text{ kHz}$
- (3) $\delta = 0.2$; $f = 20\text{ kHz}$
- (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig 12. Average forward current as a function of ambient temperature; typical values $T_j = 150\text{ °C}$

- (1) $\delta = 1$; DC
- (2) $\delta = 0.5$; $f = 20\text{ kHz}$
- (3) $\delta = 0.2$; $f = 20\text{ kHz}$
- (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig 13. Average forward current as a function of solder point temperature; typical values

8. Test information

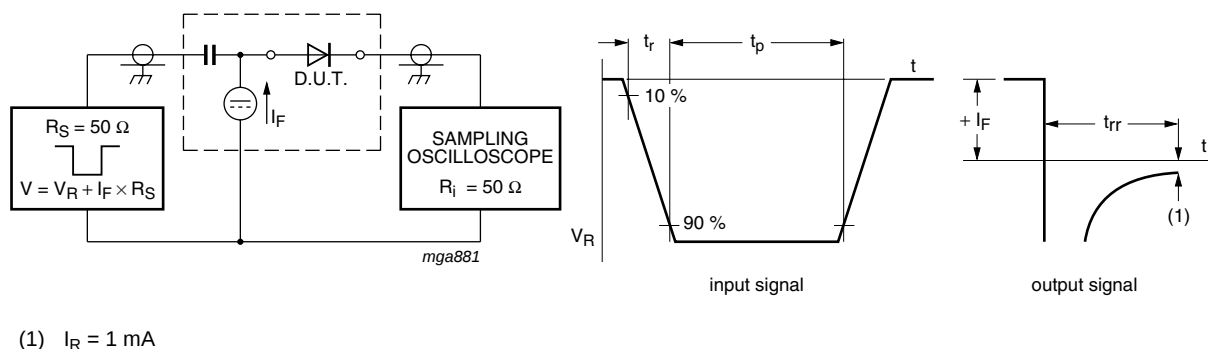


Fig 14. Reverse recovery time test circuit and waveforms

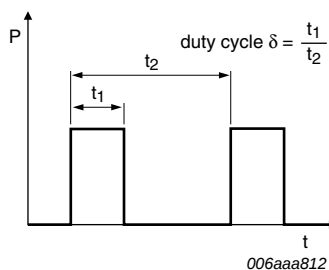


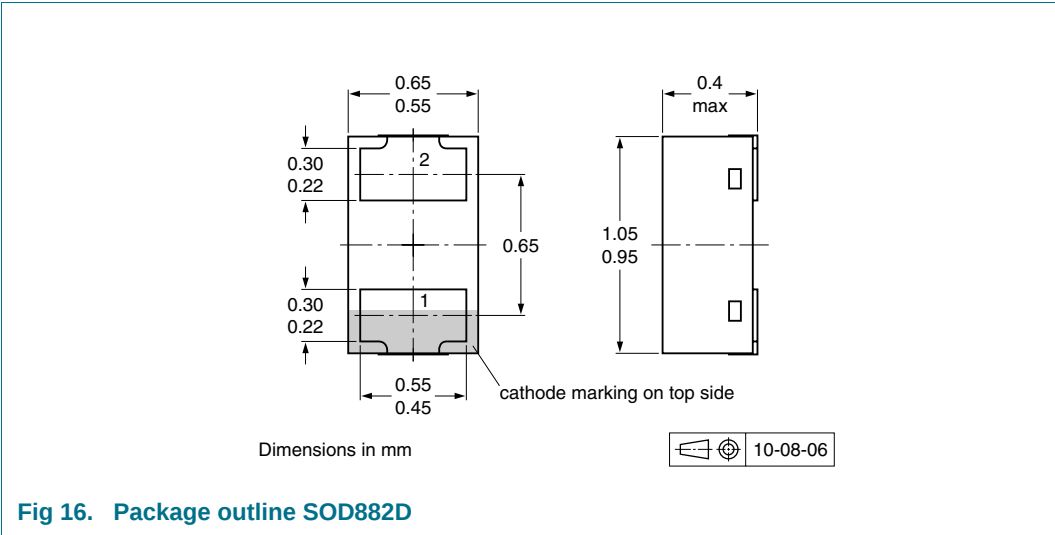
Fig 15. Duty cycle definition

The current ratings for the typical waveforms as shown in [Figure 10](#), [11](#), [12](#) and [13](#) are calculated according to the equations: $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current, $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_M \times \sqrt{\delta}$ with I_{RMS} defined as RMS current.

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

9. Package outline



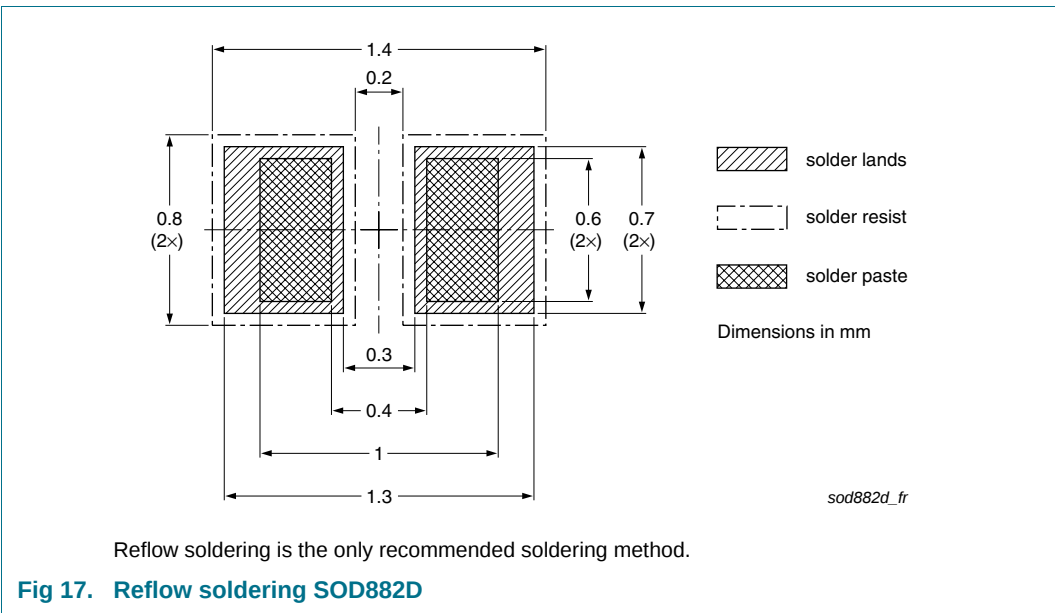
10. Packing information

Table 8. Packing methods
The indicated -xxx are the last three digits of the 12NC ordering code.[\[1\]](#)

Type number	Package	Description	Packing quantity
			10000
PMEG2005AELD	SOD882D	2 mm pitch, 8 mm tape and reel	-315

[1] For further information and the availability of packing methods, see [Section 14](#).

11. Soldering



12. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PMEG2005AELD v.1	20110510	Product data sheet	-	-

13. Legal information

13.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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15. Contents

1	Product profile	1
1.1	General description	1
1.2	Features and benefits	1
1.3	Applications	1
1.4	Quick reference data	1
2	Pinning information	2
3	Ordering information	2
4	Marking	2
4.1	Binary marking code description	2
5	Limiting values	3
6	Thermal characteristics	4
7	Characteristics	6
8	Test information	9
8.1	Quality information	9
9	Package outline	10
10	Packing information	10
11	Soldering	10
12	Revision history	11
13	Legal information	12
13.1	Data sheet status	12
13.2	Definitions	12
13.3	Disclaimers	12
13.4	Trademarks	13
14	Contact information	13
15	Contents	14

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